

Special Issue

3D Micro/Nano Printing Technologies and Advanced Materials

Message from the Guest Editor

The pursuit of miniaturization, functional complexity, and multi-material integration in modern electronics, photonics, and biomedical devices has positioned 3D micro/nano printing as a pivotal frontier in advanced manufacturing. However, realizing its full potential demands synergistic innovations in both process methodologies (e.g., multi-photon polymerization, printed hybrid electronics, microfluidics-assisted assembly) and functional materials (e.g., stimuli-responsive polymers, nano-composite inks, conductive inks). In this Special Issue, original research articles and reviews are welcome. Research areas may include (but not limited to) the following: novel micro/nano printing technology, advanced materials, smart sensing, wearable electronics and potential applications. I look forward to receiving your contributions.

Guest Editor

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About the Journal

Message from the Editor-in-Chief

Journal of Manufacturing and Materials Processing (JMMP) (ISSN 2504-4494) is a new MDPI peer-reviewed, open access venue with a focus on the scientific fundamentals and engineering methodologies of manufacturing and materials processing. We offer an online platform facilitating effective exchange of innovative scientific and engineering ideas and the dissemination of recent, original, and significant research and developmental findings. On behalf of the Editorial Board, I extend an invitation to our scientific and engineering colleagues to contribute high-quality, innovative, and ground-breaking research articles to *JMMP*.

Editor-in-Chief

Prof. Dr. Steven Y. Liang

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